

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
Commissioner of Patents and Trademarks
Washington, D.C. 20231

Re: Inventor(s): Yongsik Moon, David Mai, Kapila Wijekoon, Rajeev Bajaj, Rahul Surana, Yongqi Hu, Tony S. Kaushal, Shijian Li, Jui-Lung Li, Shi-Ping Wang, Gary Lam, and Fred C. Redeker
Title: METHOD AND APPARATUS FOR POLISHING METAL AND DIELECTRIC SUBSTRATES

Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 42 pages.
☒ Drawings totaling 6 pages, ☒ Formal ☐ Informal.
☒ Executed Declaration and Power of Attorney.
☐ Information Disclosure Statement w/ Form 1449 and References.
☒ Assignment of the invention to **Applied Materials, Inc.**
☒ Assignment Recordation Cover Sheet

FEE CALCULATION

	NUMBER OF CLAIMS FILED	LESS NUMBER PAID BY BASIC FEE	NUMBER OF EXTRA CLAIMS (Not less than zero)	LARGE ENTITY FEE
Basic Fee				\$740.00
Total Claims	34	- 20 = 14	X \$18 =	\$252.00
Independent Claims	5	- 3 = 2	X \$84 =	\$168.00
First Presentation of Multiple Dependent Claims +250				-0-
Total Filing Fee Calculation				\$1,160.00

- ☒ The Commissioner is hereby authorized to charge \$1,160.00 to Deposit Account No. 50-1074/AMAT/5803/CMP/CMP/RKK.
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074/AMAT/5803/CMP/CMP/RKK. A duplicate copy of this transmittal is enclosed.
☒ Please address all future correspondence to:

PATENT COUNSEL
APPLIED MATERIALS, INC.
Legal Affairs Department
P.O.BOX 450A
Santa Clara, CA. 95052

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner of Patents and Trademarks, U.S. Patent & Trademark Office, Assistant Commissioner for Patents Washington, DC 20231.

Express Mail Receipt No. EV 041915737 US

Date of Deposit: 12-18-01

Signature: Robert W. Mulcahy

Respectfully submitted,

Robert W. Mulcahy
Registration No. 25,436